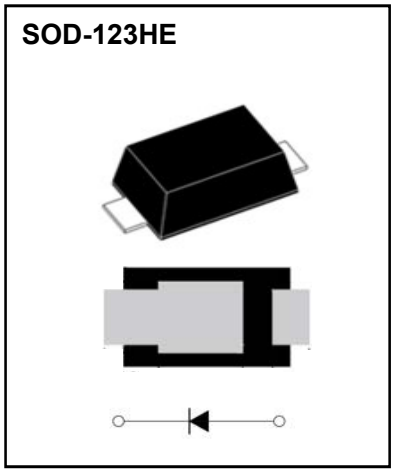
SZCJ

Shenzhen Changji Semiconductor Co., LTD.

SOD-123HE Plastic-Encapsulate Diodes

DSS22 THRU DSS210 Schottky Rectifier Diodes



Features

- $I_{F(AV)}$ 2A
- V_{RRM} 20V-100V
- High surge current capability
- Polarity: Color band denotes cathode

Applications

- Rectifier

Marking

- DSS22-DSS210 : S22-S210

Limiting Values (Absolute Maximum Rating)

Item	Symbol	Unit	Test Conditions	DSS						
				22	23	24	25	26	28	210
Repetitive Peak Reverse Voltage	V_{RRM}	V		20	30	40	50	60	80	100
Maximum RMS Voltage	V_{RMS}	V		14	21	28	35	42	56	70
Maximum DC Blocking Voltage	V_{DC}	V		20	30	40	50	60	80	100
Average Forward Current	$I_{F(AV)}$	A	60Hz Half-sine wave, Resistance load, TL=(Fig.1)	2.0						
Surge(Non-repetitive)Forward Current	I_{FSM}	A	60Hz Half-sine wave, 1 cycle, Ta=25℃	60						
Junction Temperature	T_J	℃		-55~+125			-55~+150			
Storage Temperature	T_{STG}	℃		-55 ~ +150						

Electrical Characteristics (T=25 ℃Unless otherwise specified)

Item	Symbol	Unit	Test Condition		DSS					
					22	23	24	25	26	28	210
Peak Forward Voltage	V_{FM}	V	I_{FM}=2.0A		0.55			0.70		0.85	
Peak Reverse Current	I_{RRM1}	mA	$V_{RM}=V_{RRM}$	Ta =25℃	0.5					0.01	
	I_{RRM2}			Ta =125℃	10					0.5	
Thermal Resistance(Typical)	$R_{\theta J-A}$	℃/W	Between junction and ambient		75						
	$R_{\theta J-L}$		Between junction and terminal		17						

Notes:

Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.2" x 0.2" (5.0 mm x 5.0 mm) copper pad areas

Typical Characteristics

FIG.1: FORWARD CURRENT DERATING CURVE

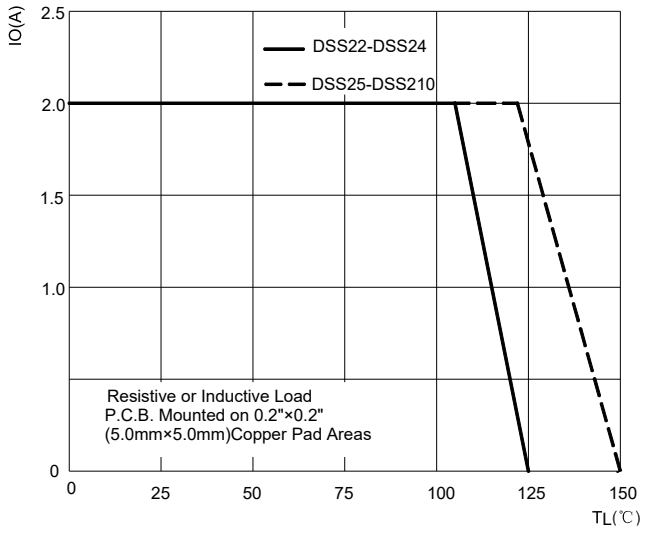


FIG.2: MAXIMUM NON-REPETITIVE FORWARD URGE CURRENT

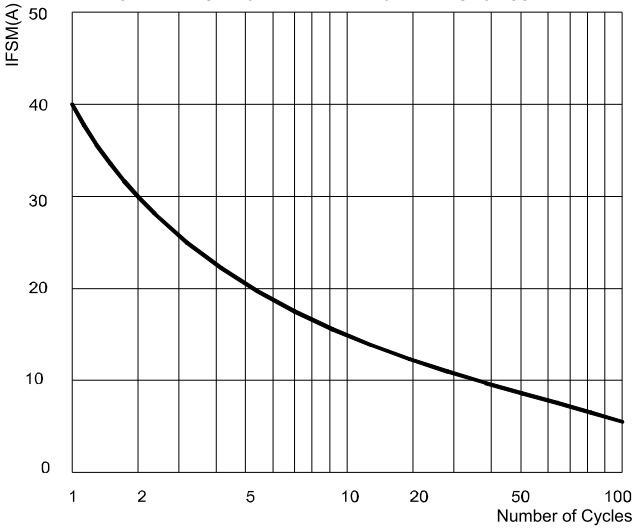


FIG.3: TYPICAL FORWARD CHARACTERISTICS

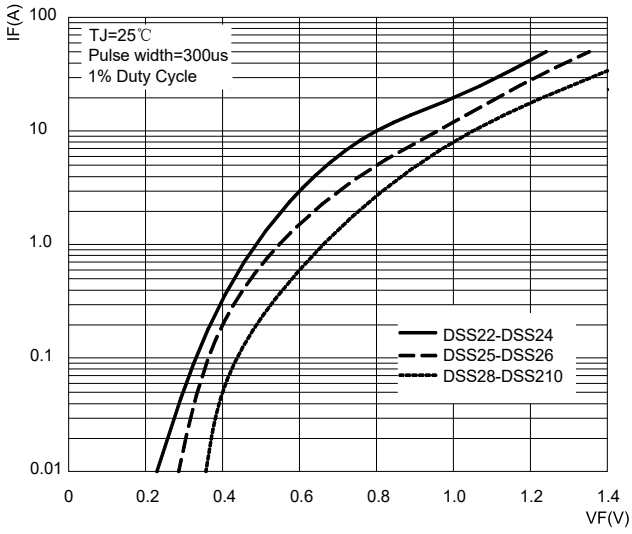
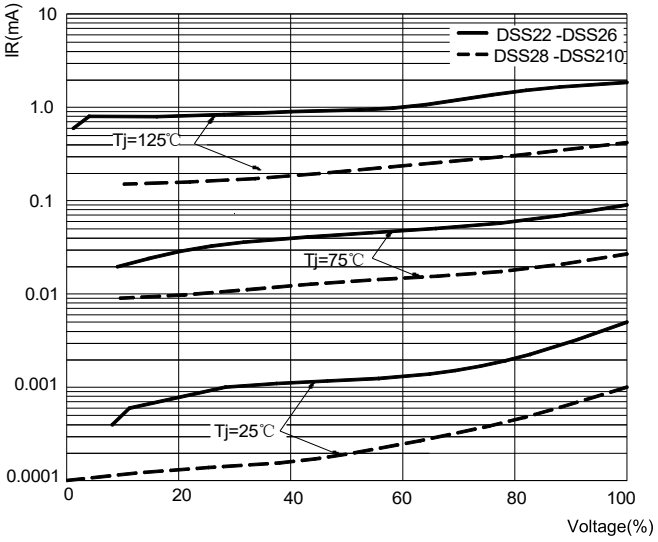
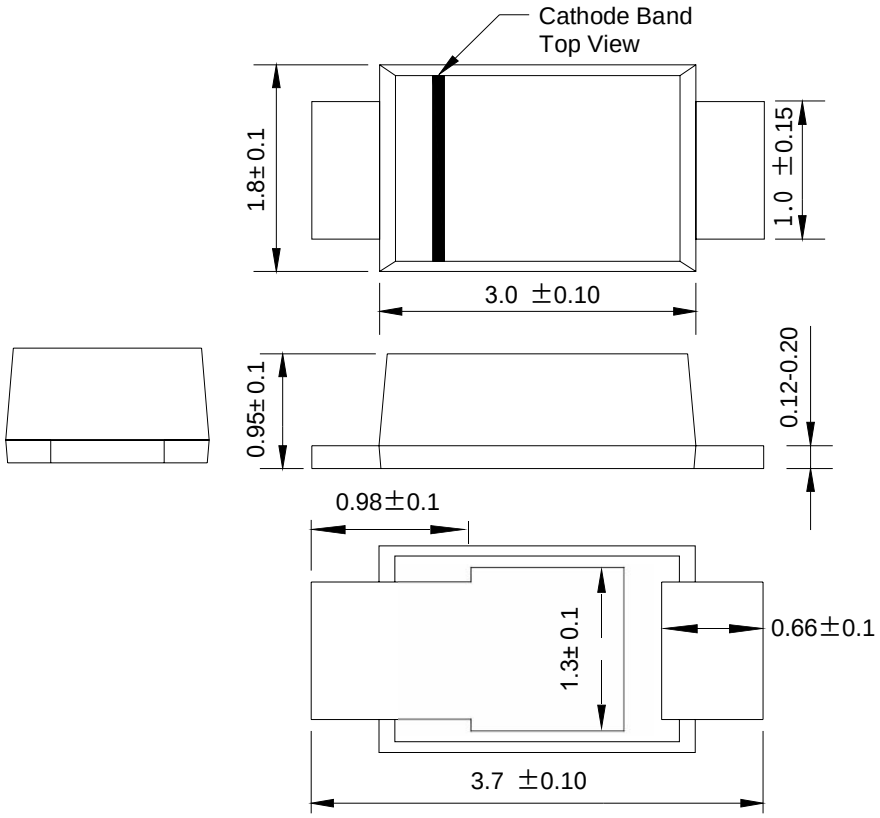


FIG.4：TYPICAL REVERSE CHARACTERISTICS



SOD-123HE Package Outline Dimensions



Dimensions in millimeters

NOTICE

SZCJ reserves the right to make modifications,enhancements,improvements,corrections or other changes without further notice to any product herein. SZCJ does not assume any liability arising out of the application or use of any product described .

Reel Taping Specifications For Surface Mount Devices-SOD-123HE

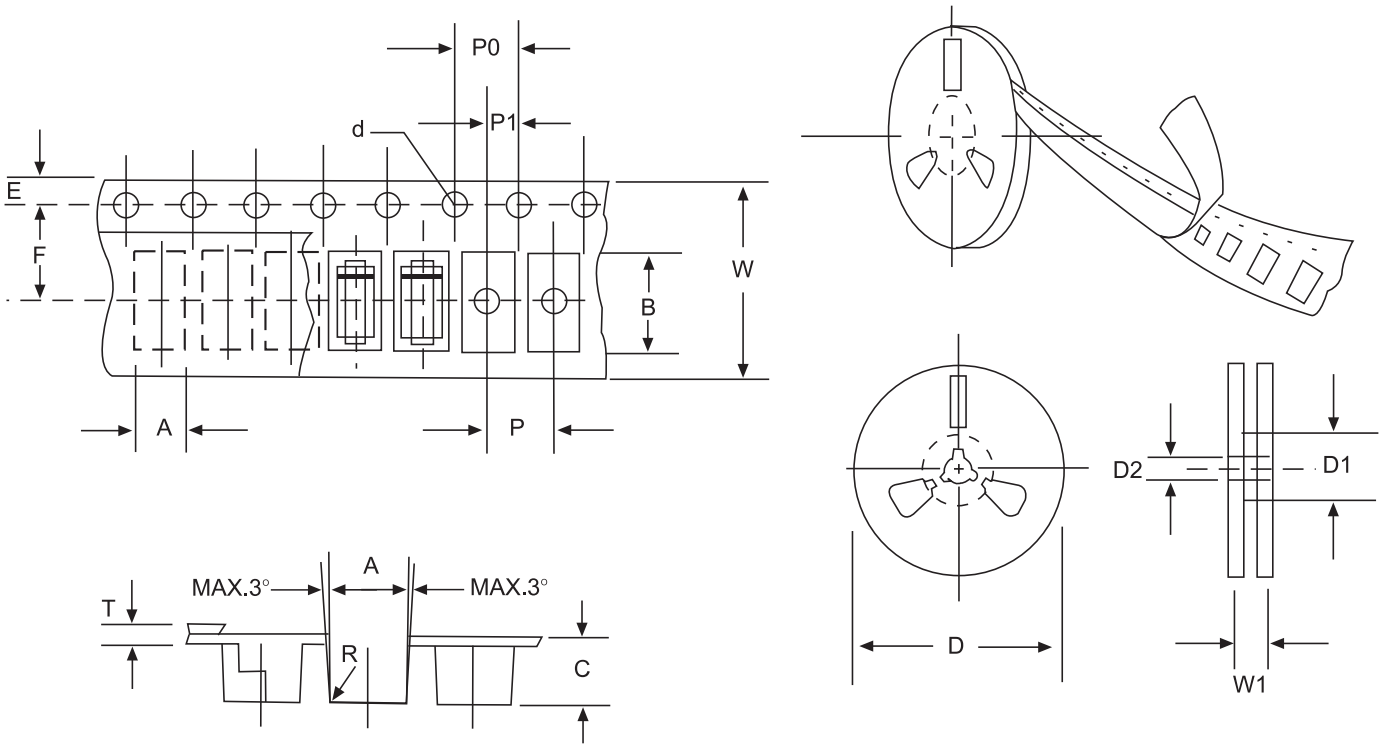


FIG:CONFIGURATION OF SURFACE MOUNTED DEVICES TAPING

ITEM	SYMBOL	SOD-123HE mm(inch)
Carrier width	A	2.05±0.1(0.081±0.004)
Carrier length	B	3.95±0.1(0.156±0.004)
Carrier depth	C	1.45±0.1(0.057±0.004)
Sprocket hole	d	1.55±0.05(0.061±0.002)
Reel outside diameter	D	178±2.0(7.0±0.079)
Reel inner diameter	D1	54±1.0(2.13±0.039)
Feed hole diameter	D2	13±0.5(0.512±0.020)
Stroket hole position	E	1.75±0.1(0.069±0.004)
Punch hole position	F	3.50±0.1(0.138±0.002)
Punch hole pitch	P	4.0±0.1(0.157±0.004)
Sprocket hole pitch	P0	4.0±0.1(0.157±0.004)
Embossment center	P1	2.0±0.1(0.079±0.004)
Totall tape thickness	T	0.21±0.25(0.008±0.010)
Tape width	W	8.0±0.2(0.315±0.008)
Reel width	W1	10.0±2.0(0.394±0.079)

NOTE:Devices are packde in accordance with EIA standard RS-481-A and specification given above.